

KAF-6303

3072 (H) x 2048 (V) Full Frame CCD Image Sensor

Description

The KAF-6303 Image Sensor is a high performance CCD (charge-coupled device) with 3072 (H) x 2048 (V) photo active pixels designed for a wide range of image sensing applications.

The sensor incorporates true two-phase CCD technology, simplifying the support circuits required to drive the sensor as well as reducing dark current without compromising charge capacity. The sensor also utilizes the TRUESENSE Transparent Gate Electrode to improve sensitivity compared to the use of a standard front side illuminated polysilicon electrode.

Table 1. GENERAL SPECIFICATIONS

| Parameter | Typical Value |
|---|---|
| Architecture | Full Frame CCD |
| Total Number of Pixels | 3088 (H) x 2056 (V) |
| Number of Active Pixels | 3072 (H) x 2048 (V) = approx. 6.3 Mp |
| Pixel Size | 9 μm (H) x 9 μm (V) |
| Active Image Size | 27.65 mm (H) x 18.48 mm (V) 33.4 mm (Diagonal) APS-H Optical Format |
| Chip Size | 29.0 mm (H) x 19.1 mm (V) |
| Saturation Signal | 100,000 e ⁻ |
| Output Sensitivity | 10 μV/e ⁻ |
| Quantum Efficiency (450, 550, 650 nm) | 40%, 52%, 65% |
| Readout Noise (10 MHz) | 15 e ⁻ rms |
| Dark Current (Accumulation Mode) | < 10 pA/cm ² |
| Dark Current Doubling Rate | 6°C |
| Dynamic Range (Saturation Signal/Dark Noise) | 76 dB |
| Maximum Data Rate | 10 MHz |
| Package | CERDIP Package (Sidebrazed) |
| Cover Glass | Clear or AR Coated, 2 Sides |

NOTE: Parameters above are specified at T = 25°C unless otherwise noted.



ON Semiconductor®

www.onsemi.com

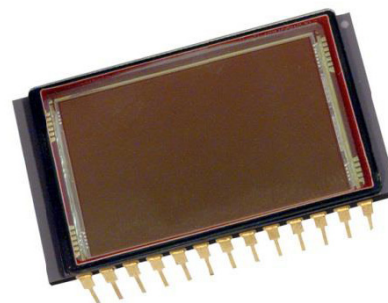


Figure 1. KAF-6303 Full Frame CCD Image Sensor

Features

- True Two Phase Full Frame Architecture
- TRUESENSE Transparent Gate Electrode for High Sensitivity
- 100% Fill Factor
- Low Dark Current

Applications

- Medical Imaging
- Scientific Imaging

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

KAF-6303

ORDERING INFORMATION

Table 2. ORDERING INFORMATION – KAF-6303 IMAGE SENSOR

| Part Number | Description | Marking Code |
|--------------------|---|-------------------------------|
| KAF-6303-AAA-CD-B2 | Monochrome, No Microlens, CERDIP Package (Sidebrazed), Clear Cover Glass with AR Coating (Both Sides), Grade 2 | KAF-6303-AAA Serial Number |
| KAF-6303-AAA-CD-AE | Monochrome, No Microlens, CERDIP Package (Sidebrazed), Clear Cover Glass with AR Coating (Both Sides), Engineering Sample | |
| KAF-6303-AAA-CP-B2 | Monochrome, No Microlens, CERDIP Package (Sidebrazed), Taped Clear Cover Glass (No Coatings), Grade 2 | |
| KAF-6303-AAA-CP-AE | Monochrome, No Microlens, CERDIP Package (Sidebrazed), Taped Clear Cover Glass (No Coatings), Engineering Sample | |

Table 3. ORDERING INFORMATION – EVALUATION SUPPORT

| Part Number | Description |
|---------------------|---------------------------------|
| KAF-6303-12-5-A-EVK | Evaluation Board (Complete Kit) |

See the ON Semiconductor *Device Nomenclature* document (TND310/D) for a full description of the naming convention used for image sensors. For reference documentation, including information on evaluation kits, please visit our web site at www.onsemi.com.

DEVICE DESCRIPTION

Architecture

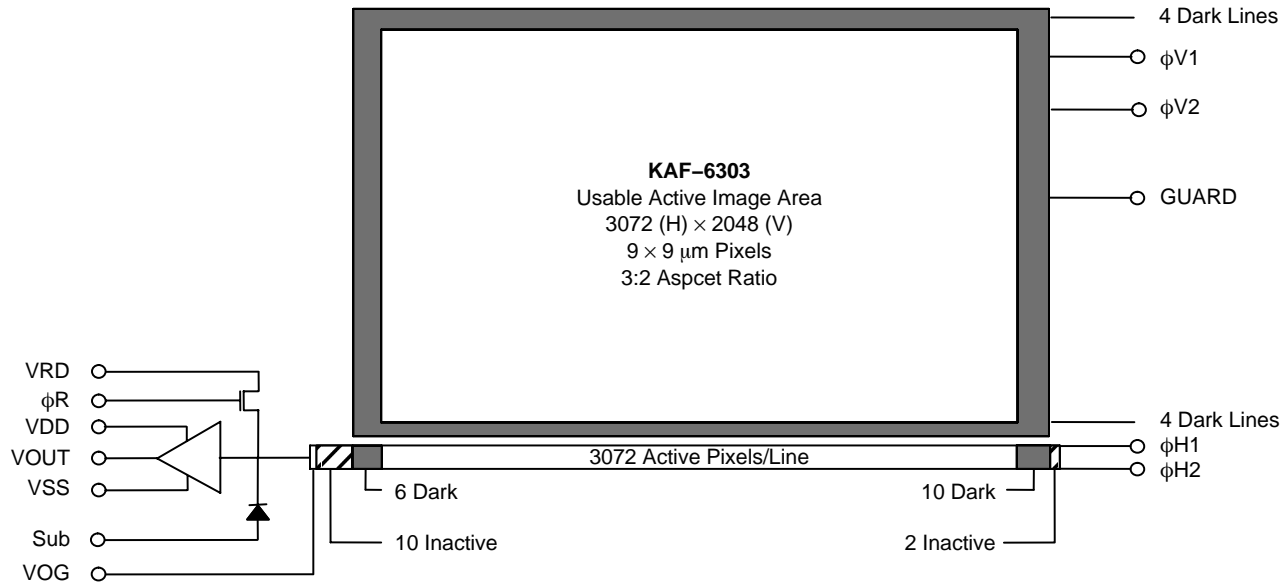


Figure 2. Block Diagram

The sensor consists of 3,088 parallel (vertical) CCD shift registers each 2,056 elements long. These registers act as both the photosensitive elements and as the transport circuits that allow the image to be sequentially read out of the sensor. The elements of these registers are arranged into a $3,072 \times 2,048$ photosensitive array surrounded by a light shielded dark reference of 16 columns and 8 rows. The parallel (vertical) CCD registers transfer the image one line at a time into a single 3,100 element (horizontal) CCD shift register. The horizontal register transfers the charge to a single output amplifier. The output amplifier is a two-stage source follower that converts the photo-generated charge to a voltage for each pixel.

Dark Reference Pixels

Surrounding the peripheral of the device is a border of light shielded pixels. This includes 6 leading and 10 trailing pixels on every line excluding dummy pixels. There are also 4 full dark lines at the start of every frame and 4 full dark lines at the end of each frame. Under normal circumstances, these pixels do not respond to light. However, dark reference pixels in close proximity to an active pixel, or the outer bounds of the chip (including the first two lines out), can scavenge signal depending on light intensity and wavelength and therefore will not represent the true dark signal.

Dummy Pixels

Within the horizontal shift register are 10 leading and 2 trailing additional shift phases that are not associated with a column of pixels from the vertical register. These pixels

contain only horizontal shift register dark current signal and do not respond to light. A few leading dummy pixels may scavenge false signal depending on operating conditions.

Image Acquisition

An electronic representation of an image is formed when incident photons falling on the sensor plane create electron-hole pairs within the sensor. These photon-induced electrons are collected locally by the formation of potential wells at each photogate or pixel site. The number of electrons collected is linearly dependent on light level and exposure time and non-linearly dependent on wavelength. When the pixel's capacity is reached, excess electrons will leak into the adjacent pixels within the same column. This is termed blooming. During the integration period, the $\phi V1$ and $\phi V2$ register clocks are held at a constant (low) level. See Figure 8.

Charge Transport

Referring again to Figure 8, the integrated charge from each photogate is transported to the output using a two-step process. Each line (row) of charge is first transported from the vertical CCD's to the horizontal CCD register using the $\phi V1$ and $\phi V2$ register clocks. The horizontal CCD is presented a new line on the falling edge of $\phi V2$ while $\phi H1$ is held high. The horizontal CCD's then transport each line, pixel by pixel, to the output structure by alternately clocking the $\phi H1$ and $\phi H2$ pins in a complementary fashion. On each falling edge of $\phi H2$, a new charge packet is transferred onto a floating diffusion and sensed by the output amplifier.

Horizontal Register

Output Structure

Charge presented to the floating diffusion (FD) is converted into a voltage and current amplified in order to drive off-chip loads. The resulting voltage change seen at the output is linearly related to the amount of charge placed on FD. Once the signal has been sampled by the system

electronics, the reset gate (ϕ_R) is clocked to remove the signal and FD is reset to the potential applied by VRD. More signal at the floating diffusion reduces the voltage seen at the output pin. In order to activate the output structure, an off-chip load must be added to the VOUT pin of the device. See Figure 3.

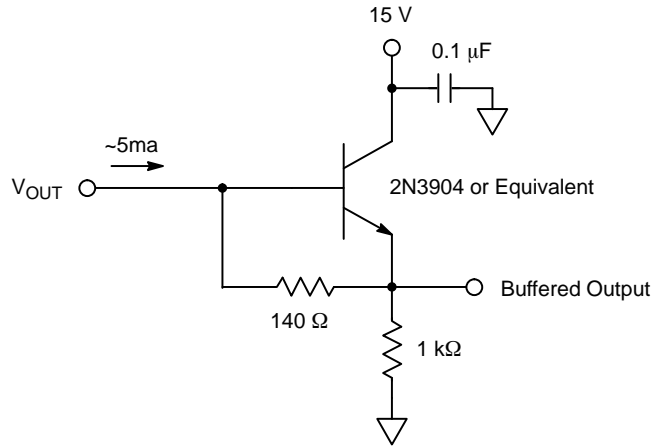


Figure 3. Typical Output Structure Load Diagram

KAF-6303

Physical Description

Pin Description and Device Orientation

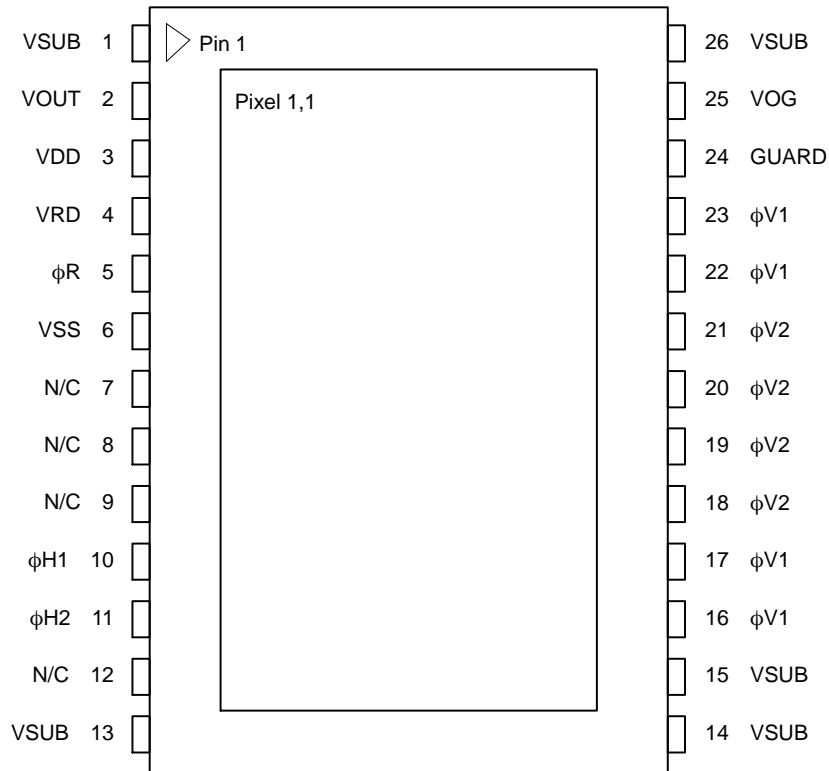


Figure 4. Pinout Diagram

NOTE: The KAF-1603 is mechanically the same and electrically identical to the KAF-0402 sensor. It is also mechanically the same as the KAF-0261 and KAF-3200 sensors. There are some electrical differences since the KAF-0261 has two outputs and two additional clock inputs. The KAF-3200 requires that pin 11 be a “No connect” and be electrically floating. Refer to their specifications for details.

Table 4. PIN DESCRIPTION

| Pin | Name | Description |
|-----|------|--------------------------------|
| 1 | VSUB | Substrate (Ground) |
| 2 | VOUT | Video Output |
| 3 | VDD | Amplifier Supply |
| 4 | VRD | Reset Drain |
| 5 | φR | Reset Clock |
| 6 | VSS | Amplifier Supply Return |
| 7 | N/C | No Connection (Open Pin) |
| 8 | N/C | No Connection (Open Pin) |
| 9 | N/C | No Connection (Open Pin) |
| 10 | φH1 | Horizontal CCD Clock – Phase 1 |
| 11 | φH2 | Horizontal CCD Clock – Phase 2 |
| 12 | N/C | No Connection (Open Pin) |
| 13 | VSUB | Substrate (Ground) |

| Pin | Name | Description |
|-----|-------|------------------------------|
| 14 | VSUB | Substrate (Ground) |
| 15 | VSUB | Substrate (Ground) |
| 16 | φV1 | Vertical CCD Clock – Phase 1 |
| 17 | φV1 | Vertical CCD Clock – Phase 1 |
| 18 | φV2 | Vertical CCD Clock – Phase 2 |
| 19 | φV2 | Vertical CCD Clock – Phase 2 |
| 20 | φV2 | Vertical CCD Clock – Phase 2 |
| 21 | φV2 | Vertical CCD Clock – Phase 2 |
| 22 | φV1 | Vertical CCD Clock – Phase 1 |
| 23 | φV1 | Vertical CCD Clock – Phase 1 |
| 24 | GUARD | Guard Ring |
| 25 | VOG | Output Gate |
| 26 | VSUB | Substrate (Ground) |

IMAGING PERFORMANCE

Table 5. SPECIFICATIONS

(All values measured at 25°C, and nominal operating conditions. These parameters exclude defective pixels.)

| Description | Symbol | Min. | Nom. | Max. | Unit | Notes | Verification Plan |
|---|-------------------------|------------------------------|-------------------------------|-------------------------------|---|-------|----------------------|
| Saturation Signal Vertical CCD Capacity Horizontal CCD Capacity Output Node Capacity | N_{SAT} | 85,000 170,000 190,000 | 100,000 200,000 220,000 | 120,000 240,000 240,000 | e ⁻ /Pixel | 1 | Design ¹¹ |
| Quantum Efficiency Red Green Blue | R_R R_G R_B | 52 42 30 | 65 52 40 | 75 62 48 | %QE | | Design ¹¹ |
| Photoresponse Non-Linearity | PRNL | - | 1.0 | 2.0 | % | 2 | Design ¹¹ |
| Photoresponse Non-Uniformity | PRNU | - | 1.0 | 3.0 | % | 3 | Die ¹⁰ |
| Dark Signal | J_{DARK} | - - | 15 3.5 | 50 10 | e ⁻ /Pix/Sec pA/cm ² | 4 | Die ¹⁰ |
| Dark Signal Doubling Temperature | | 5.0 | 6.3 | 7.5 | °C | | Design ¹¹ |
| Dark Signal Non-Uniformity | DSNU | - | 10 | 50 | e ⁻ /Pix/Sec | 5 | Die ¹⁰ |
| Dynamic Range | DR | 70 | 76 | - | dB | 6 | Design ¹¹ |
| Charge Transfer Efficiency | CTE | 0.99997 | 0.99999 | - | | | Die ¹⁰ |
| Output Amplifier DC Offset | V_{ODC} | 9.5 | 10.5 | 11.5 | V | 7 | Die ¹⁰ |
| Output Amplifier Bandwidth | f_{-3dB} | - | 45 | - | MHz | 8 | Design ¹¹ |
| Output Amplifier Sensitivity | V_{OUT}/N_{e^-} | 9 | 10 | 11 | μV/e ⁻ | | Design ¹¹ |
| Output Amplifier Output Impedance | Z_{OUT} | 175 | 200 | 2,520 | Ω | | Design ¹¹ |
| Noise Floor | n_{e^-} | - | 15 | 20 | e ⁻ | 9 | Die ¹⁰ |

- For pixel binning applications, electron capacity up to 330,000 can be achieved with modified CCD inputs. Each sensor may have to be optimized individually for these applications. Some performance parameters may be compromised to achieve the largest signals.
- Worst-case deviation from straight line fit, between 1% and 90% of V_{SAT} .
- One Sigma deviation of a 128 × 128 sample when CCD illuminated uniformly.
- Average of all pixels with no illumination at 25°C.
- Average dark signal of any of 12 × 8 blocks within the sensor (each block is 128 × 128 pixels).
- 20Log (N_{SAT} / n_{e^-}) at nominal operating frequency and 25°C.
- Video level offset with respect to ground.
- Last output amplifier stage only. Assumes 10 pF off-chip load.
- Output noise at 25°C, nominal operating frequency, and $t_{INT} = 0$.
- A parameter that is measured on every sensor during production testing.
- A parameter that is quantified during the design verification activity.

TYPICAL PERFORMANCE CURVES

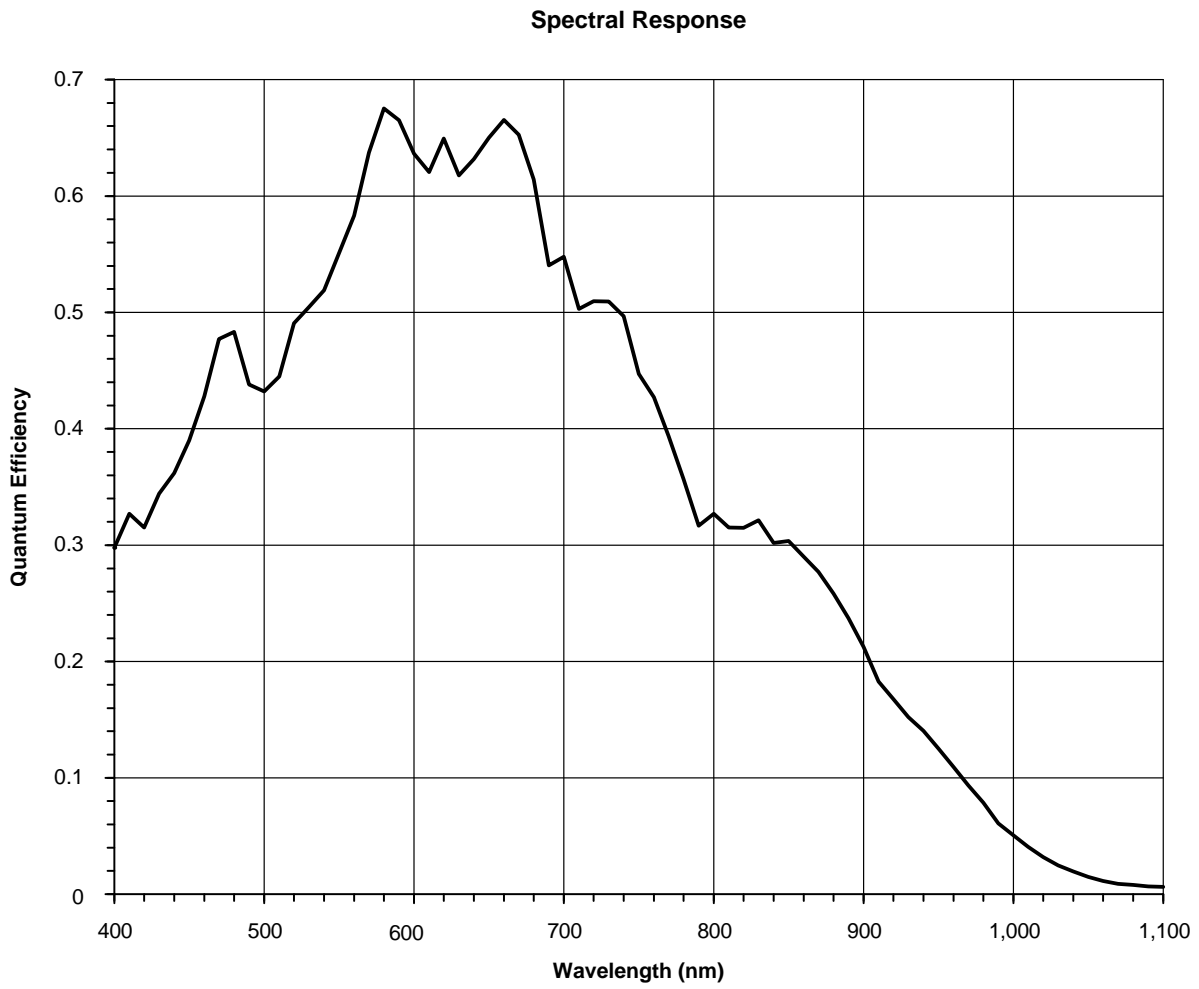


Figure 5. Typical Spectral Response

DEFECT DEFINITIONS

Table 6. SPECIFICATIONS (All tests performed at T = 25°C)

| Classification | Point Defect | | Cluster Defect | | Column Defect | |
|----------------|--------------|--------|----------------|--------|---------------|--------|
| | Total | Zone A | Total | Zone A | Total | Zone A |
| C2 | ≤ 90 | ≤ 45 | ≤ 36 | ≤ 18 | 0 | 0 |

Point Defects

Dark: A pixel which deviates by more than 6% from neighboring pixels when illuminated to 70% of saturation.

Bright: A pixel with a dark current greater than 10,000 e⁻/pixel/sec at 25°C.

Cluster Defect

A grouping of not more than 5 adjacent point defects.

Column Defect

A grouping of > 5 contiguous point defects along a single column.

A column containing a pixel with dark current > 30,000 e⁻/pix/sec at 25°C (Bright column).

A column that does not meet the CTE specification for all exposures less than the specified Max sat. signal level and greater than 2 ke⁻.

A column that loses > 250 e⁻ under 2 ke⁻ illumination.

Neighboring Pixels

The surrounding 128 × 128 pixels or ±64 columns/rows.

Defect Separation

Column and cluster defects are separated by no less than two (2) pixels in any direction (excluding single pixel defects).

Defect Region Exclusion

Defect region excludes the outer two (2) rows and columns at each side/end of the sensor.

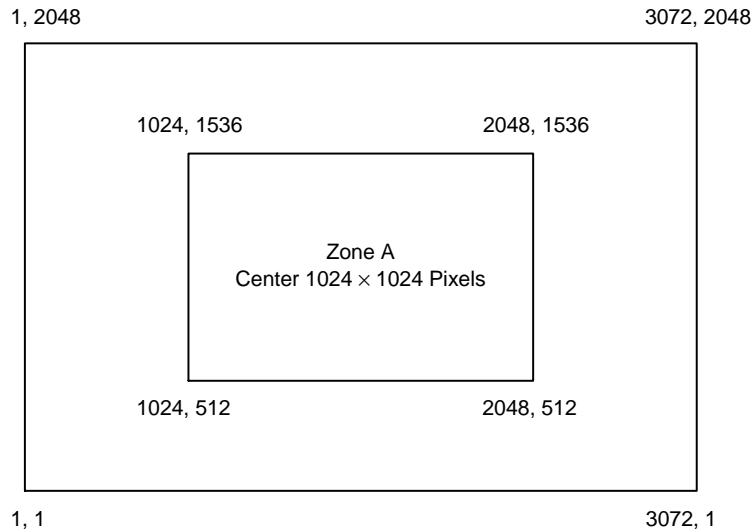


Figure 6. Active Pixel Region

OPERATION

Table 7. ABSOLUTE MAXIMUM RATINGS

| Description | Symbol | Minimum | Maximum | Unit | Notes |
|----------------------------|-------------|---------|---------|------|-------|
| Diode Pin Voltages | V_{DIODE} | 0 | 20 | V | 1, 2 |
| Gate Pin Voltages – Type 1 | V_{GATE1} | -16 | 16 | V | 1, 3 |
| Gate Pin Voltages – Type 2 | V_{GATE2} | 0 | 16 | V | 1, 4 |
| Inter-Gate Voltages | V_{g-g} | - | 16 | V | 5 |
| Output Bias Current | I_{OUT} | - | -10 | mA | 6 |
| Output Load Capacitance | C_{LOAD} | - | 15 | pF | 6 |
| Storage Temperature | T_{ST} | 0 | 70 | °C | |
| Humidity | RH | 5 | 90 | % | 7 |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Referenced to pin VSUB.
2. Includes pins: VRD, VDD, VSS, VOUT, GUARD.
3. Includes pins: $\phi V1$, $\phi V2$, $\phi H1$, $\phi H2$.
4. Includes pins: ϕR , VOG.
5. Voltage difference between overlapping gates. Includes: $\phi V1$ to $\phi V2$, $\phi H1$ to $\phi H2$, $\phi V2$ to $\phi H1$, $\phi H2$ to VOG.
6. Avoid shorting output pins to ground or any low impedance source during operation.
7. T = 25°C. Excessive humidity will degrade MTTF.

Table 8. DC BIAS OPERATING CONDITIONS

| Description | Symbol | Minimum | Nominal | Maximum | Unit | Maximum DC Current (mA) | Notes |
|-------------------------|-----------|---------|---------|---------|------|-------------------------|-------|
| Reset Drain | V_{RD} | 10.5 | 11.0 | 11.5 | V | 0.01 | |
| Output Amplifier Return | V_{SS} | 1.5 | 2.0 | 2.5 | V | 0.45 | |
| Output Amplifier Supply | V_{DD} | 14.5 | 15 | 15.5 | V | I_{OUT} | |
| Substrate | V_{SUB} | 0 | 0 | 0 | V | 0.01 | |
| Output Gate | V_{OG} | 3.75 | 4.0 | 5.0 | V | 0.01 | |
| Guard Ring | V_{LG} | 8.0 | 10.0 | 12.0 | V | 0.01 | |
| Video Output Current | I_{OUT} | - | -5 | -10 | mA | - | 1 |

1. An output load sink must be applied to VOUT to activate output amplifier – see Figure 3.

AC Operating Conditions

Table 9. CLOCK LEVELS

| Description | Symbol | Level | Min. | Nom. | Max. | Unit | Effective Capacitance |
|--------------------------------|-----------|-------|-------|-------|------|------|-----------------------------|
| Vertical CCD Clock – Phase 1 | $\phi V1$ | Low | -10.5 | -10 | -9.5 | V | 82 nF (All $\phi V1$ Pins) |
| Vertical CCD Clock – Phase 1 | $\phi V1$ | High | 0.5 | 1.0 | 1.5 | V | 82 nF (All $\phi V1$ Pins) |
| Vertical CCD Clock – Phase 2 | $\phi V2$ | Low | -10.5 | -10.0 | -9.5 | V | 820 nF (All $\phi V2$ Pins) |
| Vertical CCD Clock – Phase 2 | $\phi V2$ | High | 0.5 | 1.0 | 1.5 | V | 820 nF (All $\phi V2$ Pins) |
| Horizontal CCD Clock – Phase 1 | $\phi H1$ | Low | -6.0 | -3.0 | -3.0 | V | 400 pF |
| Horizontal CCD Clock – Phase 1 | $\phi H1$ | High | 4.0 | 7.0 | 7.0 | V | 400 pF |
| Horizontal CCD Clock – Phase 2 | $\phi H2$ | Low | -6.0 | -3.0 | -3.0 | V | 400 pF |
| Horizontal CCD Clock – Phase 2 | $\phi H2$ | High | 4.0 | 7.0 | 7.0 | V | 400 pF |
| Reset Clock | ϕR | Low | -4.0 | -3.0 | -2.0 | V | 10 pF |
| Reset Clock | ϕR | High | 3.5 | 4.0 | 5.0 | V | 10 pF |

1. All pins draw less than 10 μA DC current.
2. Capacitance values relative to V_{SUB} .

TIMING

Table 10. REQUIREMENTS AND CHARACTERISTICS

| Description | Symbol | Minimum | Nominal | Maximum | Unit | Notes |
|--|---------------|---------|---------|---------|---------|---------|
| ϕ H1, ϕ H2 Clock Frequency | f_H | – | 4 | 15 | MHz | 1, 2, 3 |
| ϕ V1, ϕ V2 Clock Frequency | f_V | – | 25 | 50 | kHz | 1, 2, 3 |
| Pixel Period (1 Count) | t_e | 67 | 250 | – | ns | |
| ϕ H1, ϕ H2 Set-up Time | $t_{\phi HS}$ | 0.5 | 1 | – | μ s | |
| ϕ V1, ϕ V2 Clock Pulse Width | $t_{\phi V}$ | 10 | 20 | – | μ s | 2 |
| Reset Clock Pulse Width | $t_{\phi R}$ | 10 | 20 | – | ns | 4 |
| Readout Time | $t_{READOUT}$ | 531 | 1,719 | – | ms | 5 |
| Integration Time | t_{INT} | – | – | – | | 6 |
| Line Time | t_{LINE} | 258.2 | 836 | – | μ s | 7 |

1. 50% duty cycle values.
2. CTE may degrade above the nominal frequency.
3. Rise and fall times (10/90% levels) should be limited to 5–10% of clock period. Cross-over of register clocks should be between 40–60% of amplitude.
4. ϕ R should be clocked continuously.
5. $t_{READOUT} = (2056 \cdot t_{LINE})$.
6. Integration time (t_{INT}) is user specified. Longer integration times will degrade noise performance.
7. $t_{LINE} = (3 \cdot t_{\phi V}) + t_{\phi HS} + 3100 + t_e$.

Frame Timing

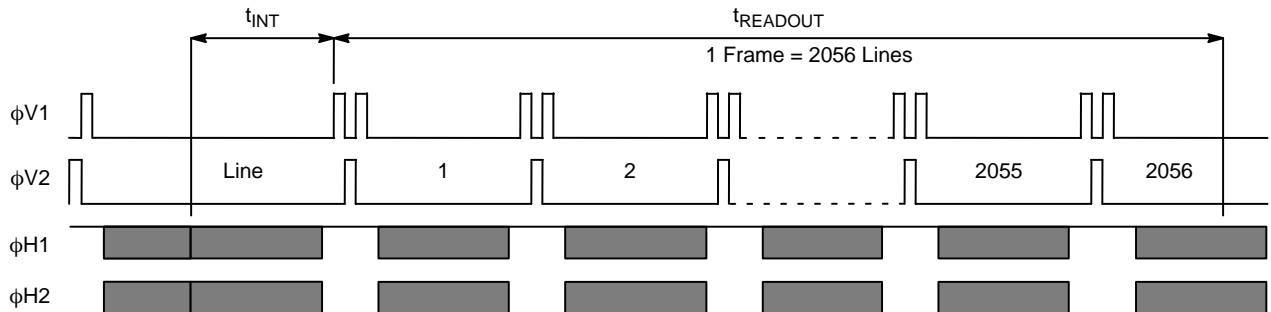
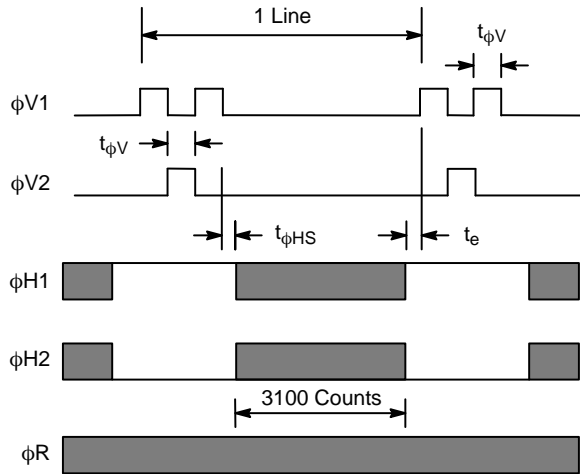


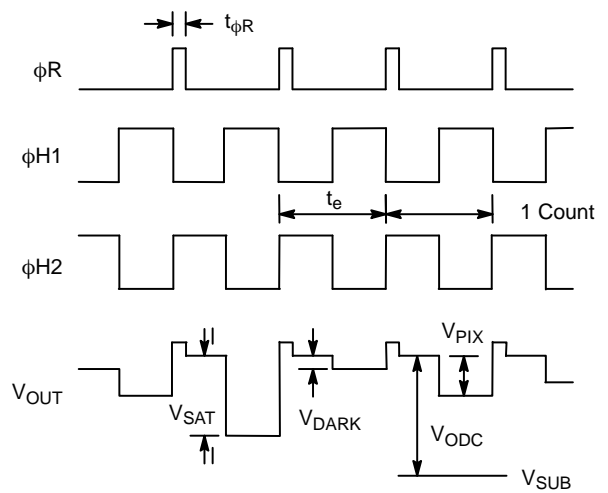
Figure 7. Frame Timing

Line Timing (Each Output)

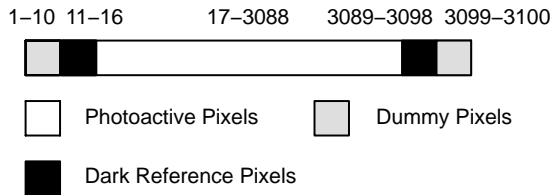
Line Timing Detail



Pixel Timing Detail



Line Content



- V_{SAT} Saturated pixel video output signal
- V_{DARK} Video output signal in no-light situation, not zero due to J_{DARK}
- V_{PIX} Pixel video output signal level, more electrons = more negative*
- V_{ODC} Video level offset with respect to V_{SUB}
- V_{SUB} Analog ground

* See Image Acquisition section (Page 3).

Figure 8. Timing Diagrams

STORAGE AND HANDLING

Table 11. STORAGE CONDITIONS

| Description | Symbol | Minimum | Maximum | Unit | Notes |
|-----------------------|-----------------|---------|---------|------|-------|
| Storage Temperature | T _{ST} | 0 | 70 | °C | 1 |
| Operating Temperature | T _{OP} | -60 | 60 | °C | |

1. Storage toward the maximum temperature will accelerate color filter degradation.

For information on ESD and cover glass care and cleanliness, please download the *Image Sensor Handling and Best Practices* Application Note (AN52561/D) from www.onsemi.com.

For information on soldering recommendations, please download the *Soldering and Mounting Techniques Reference Manual* (SOLDERRM/D) from www.onsemi.com.

For quality and reliability information, please download the *Quality & Reliability Handbook* (HBD851/D) from www.onsemi.com.

For information on device numbering and ordering codes, please download the *Device Nomenclature* technical note (TND310/D) from www.onsemi.com.

For information on Standard terms and Conditions of Sale, please download [Terms and Conditions](#) from www.onsemi.com.

MECHANICAL INFORMATION

Completed Assembly

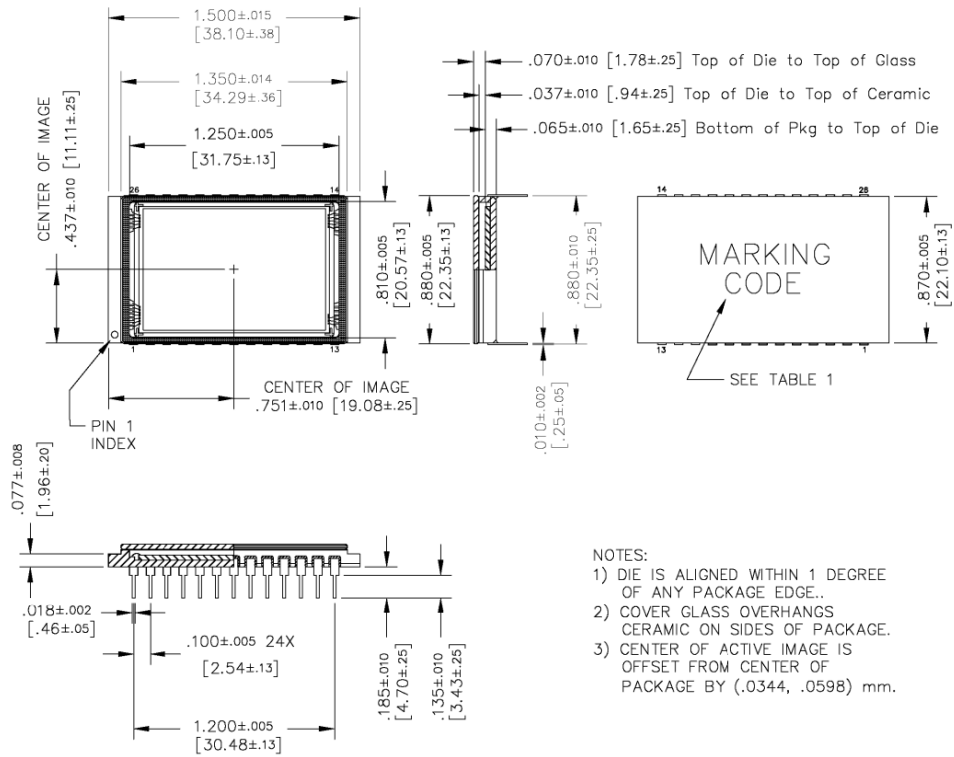
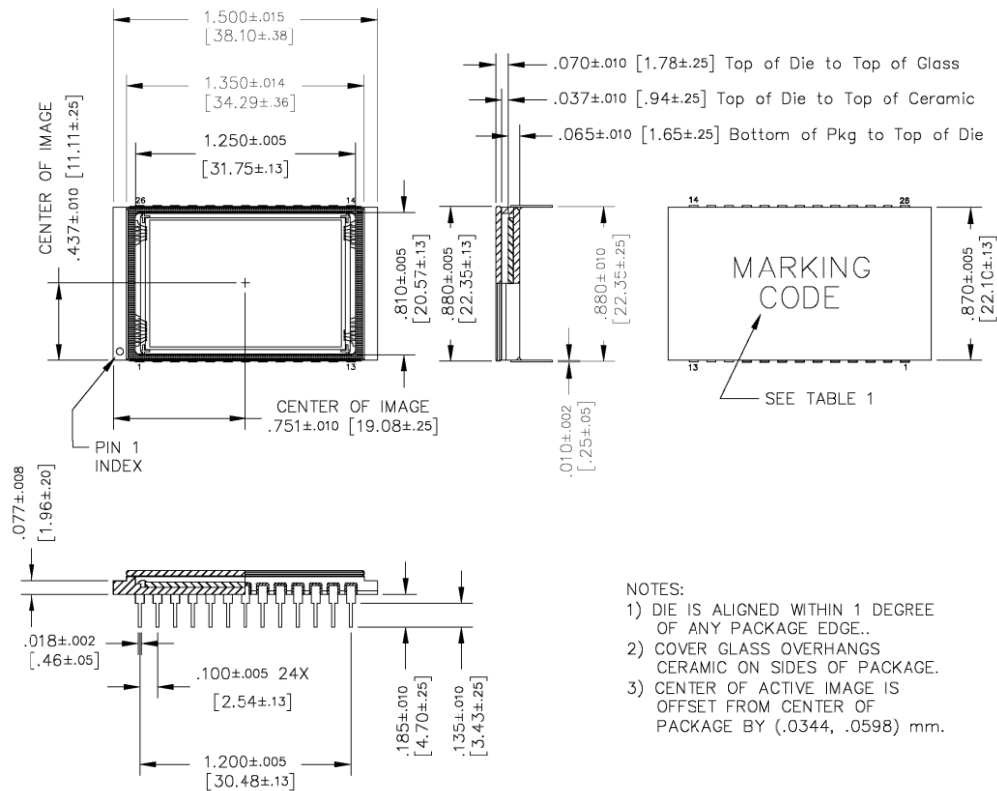



Figure 9. Completed Assembly (1 of 2)



- NOTES:
- 1) DIE IS ALIGNED WITHIN 1 DEGREE OF ANY PACKAGE EDGE..
 - 2) COVER GLASS OVERHANGS CERAMIC ON SIDES OF PACKAGE.
 - 3) CENTER OF ACTIVE IMAGE IS OFFSET FROM CENTER OF PACKAGE BY (.0344, .0598) mm.

Figure 10. Completed Assembly (2 of 2)

ON Semiconductor and the  are registered trademarks of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries. SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
 Literature Distribution Center for ON Semiconductor
 P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
 Phone: 421 33 790 2910
Japan Customer Focus Center
 Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com
Order Literature: <http://www.onsemi.com/orderlit>
 For additional information, please contact your local Sales Representative



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.